

Title (en)

DEVICE FOR TOUCH-FREE TEMPERATURE MEASUREMENT

Publication

EP 0235627 A3 19890329 (DE)

Application

EP 87101893 A 19870211

Priority

DE 3607368 A 19860306

Abstract (en)

[origin: EP0235627A2] In the device, a component (10) has arranged on it an element (11) of a material having a different coefficient of thermal expansion than the component (10) itself. In the event of a change in temperature, an elastic, mechanical deformation of the element (11) is induced, which changes the distance from a distance sensor (12). This change in distance is a measure of the temperature to be measured. The device is of a simple design and is inexpensive. It can be used for virtually all commercially known distance sensors. <IMAGE>

IPC 1-7

G01K 5/50; **G01K 5/70**

IPC 8 full level

G01K 5/50 (2006.01); **G01K 5/62** (2006.01); **G01K 5/70** (2006.01)

CPC (source: EP)

G01K 5/50 (2013.01); **G01K 5/62** (2013.01)

Citation (search report)

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- [XP] PATENT ABSTRACTS OF JAPAN, Band 10, Nr. 371 (P-526)[2428], 11. Dezember 1986; & JP 61165628 A (YASKAWA ELECTRIC MFG CO., LTD) 26-07-1986
- [X] PATENT ABSTRACTS OF JAPAN, Band 9, Nr. 151 (P-367)[1874], 26. Juni 1985; & JP 60027827 A (NICHIDEN ANELVA K.K.) 12-02-1985
- [X] PATENT ABSTRACTS OF JAPAN, Band 9, Nr. 120 (P-358)[1843], 24. Mai 1985; & JP 60004830 A (NICHIDEN ANELVA K.K.) 11-01-1985
- [A] PATENT ABSTRACTS OF JAPAN, Band 5, Nr. 175 (P-88)[847], 11. November 1981; & JP 56103333 A (TOKYO SHIBAURA DENKI K.K.) 18-08-1981

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